Cleaning Method of Semiconductor Wafer

Abstract

[Problem]

To provide a removal method of wax capable of uniformly removing the wax adhering to a wafer surface and reducing the problems of re-adhesion of particles and filter clogging of a cleaning bath during cleaning.

[Means for solving the problem]

A cleaning method of a semiconductor wafer of removing wax, which is adhering to a wafer surface, by using cleaning liquid, the cleaning method is characterized in that the cleaning liquid contains microbubbles.

FIG. 2